L Number	Hits	Search Text	DB	Time stamp
1	0	substrate same roughness near3 back near2	USPAT;	2003/10/01
*	J	surface same radius	US-PGPUB;	11:00
		Surrace same radius	EPO; JPO;	111.00
i				,
			DERWENT;	
		1	IBM_TDB	0000/10/01
2	1		USPAT;	2003/10/01
		surface same diameter	US-PGPUB;	11:02
1			EPO; JPO;	
i i			DERWENT;	
1			IBM_TDB	:
3	7		USPAT;	2003/10/01
		(varied or varying or varies or change)	US-PGPUB;	11:04
		with roughness	EPO; JPO;	
		_	DERWENT;	
			IBM TDB	
-	26	wafer same roughness same backside near2	USPAT	2003/09/30
		surface		12:57
_	1	N 100 20 20 20 20 20	USPAT	2003/09/30
	*		JULAI	12:56
_	0		USPAT	2003/09/30
-	١		USPAI	12:56
				I
-	0		USPAT	2003/09/30
	_			12:56
-	0		USPAT	2003/09/30
				12:56
-	0		USPAT	2003/09/30
				12:56
- 1	1		USPAT	2003/09/30
				12:56
-	0		USPAT	2003/09/30
1	_			12:56
1_	0		USPAT	2003/09/30
1	•		001711	12:56
ł	0		USPAT	2003/09/30
-	· ·		USFAI	12:56
	9		HC DCDHD.	2003/10/01
_	9	wafer same roughness same backside near2	US-PGPUB;	
		surface	EPO; JPO;	10:59
			DERWENT;	
1			IBM_TDB	0000/00/00
-	32	wafer same roughness near3 backside near2	USPAT;	2003/09/30
		surface	US-PGPUB;	14:57
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	wafer same roughness near3 backside near2	USPAT;	2003/09/30
	_	surface same radius	US-PGPUB;	14:57
	l	· · · · · · · · · · · · · · · · · · ·	EPO; JPO;	
			DERWENT;	
	l		IBM TDB	
_	,	wafer same roughness near3 back near2	USPAT;	2003/10/01
[·	+	water same roughness hears back hearz surface same radius	US-PGPUB;	11:00
		Surrace Same radius		11.00
			EPO; JPO;	
	İ		DERWENT;	
	_		IBM_TDB	0000465455
-	3	wafer same back near2 surface same	USPAT;	2003/09/30
		(varied or various or change)near3	US-PGPUB;	15:17
	!	roughness	EPO; JPO;	
1			DERWENT;	
1			IBM_TDB	